

REMARKS

Applicants wish to thank Examiner Kiliman for the helpful and courteous discussion with Applicants' Representative on January 25, 2005. As discussed, Applicants submit herewith a corrected Terminal Disclaimer.


In addition, also as discussed, Applicants submit Certified English Translations of the Japanese priority documents of the present invention, JP 2000-256775 and JP 2000-262611, filed **August 28 and 31, 2000**, respectively. Applicants have thus perfected their claim to priority. This also removes the corresponding Japanese and European applications of US 6,534,176 (filed **December 6, 2000**) as well as the US patent as prior art references. JP 2001-163613 published **June 19, 2001**, and EP 1106574 published **June 13, 2001**. See the attached Derwent Search Report for the publication dates.

This amendment was not earlier presented because the error was not earlier detected. Applicants submit that the amendment does not require further search or consideration. No new matter has been added. Entry and favorable consideration are respectfully requested.

Applicants submit that the present application remains in condition for allowance and the Examiner is requested to pass this case to Issue.

Respectfully submitted,

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L1 ANSWER 1 OF 1 WPINDEX C08K009-08 2004 THOMSON DERWENT on STN
ACCESSION NUMBER: 2001-354307 [37] WPINDEX
DOC. NO. CPI: C2001-109748
TITLE: Laminated scaly silica particles, useful in adhesives and
for forming heat insulating coatings, consist of
secondary particles of foliar silica overlaid one on
another and aligned face-to-face in parallel.
DERWENT CLASS: A60 E36
INVENTOR(S): FUJII, A; INOUE, M; MINOHARA, S; OHBA, Y; SASAKI, T;
TERASE, K
PATENT ASSIGNEE(S): (ASAG) ASAHI GLASS CO LTD; (DOHK-N) DOHKAI CHEM IND CO
LTD; (DOKA-N) DOKAI KAGAKU KOGYO KK
COUNTRY COUNT: 28
PATENT INFORMATION:

PATENT NO	KIND	DATE	WEEK	LA	PG	MAIN	IPC
US 2001003358	A1	20010614	(200137)*		38	C08K009-08	
JP 2001163613	A	20010619	(200140)		26	C01B033-12	
EP 1106574	A1	20010613	(200141)	EN		C01B033-12	
R: AL AT BE CH CY DE DK ES FI FR GB GR IE IT LI LT LU LV MC MK NL PT RO SE SI TR							
JP 2002030251	A	20020131	(200212)		14	C09D201-00	
US 6534176	B2	20030318	(200322)			C09C001-04	---
EP 1106574	B1	20040303	(200417)	EN		C01B033-12	
R: CH DE FR GB IT LI NL							

APPLICATION DETAILS:

PATENT NO	KIND	APPLICATION	DATE
US 2001003358	A1	US 2000-729822	20001206
JP 2001163613	A	JP 1999-351182	19991210
EP 1106574	A1	EP 2000-126481	20001207
JP 2002030251	A	JP 2000-206264	20000707
US 6534176	B2	US 2000-729822	20001206
EP 1106574	B1	EP 2000-126481	20001207

PRIORITY APPLN. INFO: JP 2000-206264 20000707; JP 1999-351182
19991210; JP 2000-139659 20000512

INT. PATENT CLASSIF.:

MAIN: C01B033-12; C08K009-08; C09C001-04; C09D201-00
SECONDARY: B32B005-16; C08J009-32; C08K003-36; C08K007-00;
C08L101-16; C09D001-00; C09D007-12; C09J011-04

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